## **Overview**

## HP EliteBook 735 G6 Notebook PC



- 1. HD and IR Camera (Optional)
- 2. Ambient Light Sensor (Optional)
- 3. IR Camera LEDs (Optional)
- 4. Internal Microphones
- 5. HP Privacy Camera Shutter
- 6. HD Camera LED

#### Left

- 7. Clickpad
- 8. Smartcard Reader (Optional)
- 9. USB 3.1 Gen 1 Charging Port
- 10. Vents
- 11. Security Lock Slot (Lock sold separately)
- 12. Power Button



## **Overview**



- 1. Power Connector
- 2. USB Type-C<sup>™</sup>
- 3. Docking Connector
- 4. Ethernet Port
- 5. HDMI Port (Cable not included)

- Right
- 6. USB 3.1 Gen 1 port
- 7. Audio Combo Jack
- 8. SIM Card Slot<sup>1</sup>
- 9. Touch Fingerprint Sensor (Optional)
- 10. Pointstick

1. All units have a SIM card slot and icon but units that do not support WWAN are shipped with a non-removable SIM slot plug



### **Overview**

### AT A GLANCE

- Eye-catching Ultraslim design, premium precision-crafted machined aluminum (CNC), seamless formed aluminum chassis for clean, crisp, premium look and feel
- Choice of 2nd Generation AMD Ryzen<sup>™</sup> PRO processors
- Designed to support all HP docking options including HP's traditional Ultraslim mechanical dock and all-new Thunderbolt™ dock<sup>1</sup>
- Featuring HP Collaboration Keyboard with Clickpad to manage most commonly used conferencing functions with a single keystroke
- Innovative world-facing third mic improves inbound ambient noise cancellation while 360 degree mic pick-up allows everyone to clearly hear and be heard
- Optional ant-glare touch displays with ambient light sensor
- Choice of displays:
   33.8 cm (14.0") diagonal FHD IPS anti-glare LED-backlit, non-touch, 250 cd/m<sup>2</sup>, 45% NTSC
   33.8 cm (14.0") diagonal FHD IPS anti-glare LED-backlit non-touch 400 cd/m<sup>2</sup>, 72% NTSC
   33.8cm (14.0") diagonal FHD IPS anti-glare LED-backlit non-touch, 1000 cd/m2, 72% NTSC with HP Sure View
   33.8cm (14.0") diagonal FHD Anti-Glare On-Cell LED-backlit touch, 250 cd/m2, 45% NTSC
- Enterprise grade security with HP SureStart, HP Privacy Camera<sup>1</sup>, HP Sure View<sup>4</sup>, HP Sure Run, HP Sure Recover, HP Sure Click, HP Sure Sense<sup>5</sup>, SmartCard Reader<sup>1</sup> and Touch Fingerprint reader<sup>1</sup>
- Preinstalled with Windows 10 versions or FreeDOS
- Supports fast charging (50% in 30 minutes) with no impact on battery recharge cycles<sup>2</sup>
- Flexible wireless connectivity options
- Passed MIL-STD 810G tests<sup>3</sup>
- 1. Sold separately or as an optional feature.

2. HP Elite notebooks up to 50% within 30 minutes when the system is off or in standby mode. Power adapter with a minimum capacity of 65 watts is required. After charging has reached 50% capacity, charging will return to normal. Charging time may vary +/-10% due to System tolerance.

3. MIL STD 810G testing is not intended to demonstrate fitness for U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.

4. HP Sure View G3 integrated privacy screen is an optional feature that must be configured at purchase and is designed to function in landscape orientation. Available in Q3'19.

5. HP Sure Sense requires Windows 10. See product specifications for availability.

#### NOTE: See important legal disclosures for all listed specs in their respective features sections.



### Features

#### **PRODUCT NAME**

HP EliteBook 735 G6 Notebook PC

#### **OPERATING SYSTEM**

Windows 10 Pro 64<sup>1</sup> Windows 10 Pro 64 (National Academic License)<sup>2</sup> Windows 10 Home 64<sup>1</sup> Windows 10 Home Single Language 64<sup>1</sup> Windows 10 Pro (Windows 10 Enterprise available with a Volume Licensing Agreement)<sup>1</sup> FreeDOS

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com/.

2. Some devices for academic use will automatically be updated to Windows 10 Pro Education with the Windows 10 Anniversary Update. Features vary; see https://aka.ms/ProEducation for Windows 10 Pro Education feature information.

NOTE: Your product does not support Windows 8 or Windows 7

In accordance with Microsoft's support policy, HP does not support the Windows<sup>®</sup> 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows<sup>®</sup> 8 or Windows 7 drivers on http://www.support.hp.com.

### PROCESSORS

AMD Ryzen<sup>™</sup> 7 PRO 3700U APU with Radeon<sup>™</sup> Vega 10 Graphics (2.3 GHz base clock, up to 4 GHz max boost clock, 4 MB L3 cache, 4 cores)<sup>3,4,5</sup>

AMD Ryzen<sup>™</sup> 5 PRO 3500U APU with Radeon<sup>™</sup> Vega 8 Graphics (2.1 GHz base clock, up to 3.7 GHz max boost clock, 4 MB L3 cache, 4 cores)<sup>3,4,5</sup>

AMD Ryzen<sup>™</sup> 3 PRO 3300U APU with Radeon<sup>™</sup> Vega 6 Graphics (2.1 GHz base clock, up to 3.5 GHz max boost clock, 4 MB L3 cache, 4 cores)<sup>3,4,5</sup>

#### **Processor Family**

2nd Gen AMD<sup>®</sup> Ryzen<sup>™</sup> PRO APU processor<sup>5</sup>

Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.
 Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. AMD's numbering is not a measurement of clock speed.
 In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.

#### CHIPSET

Chipset is integrated with processor



### **Features**

#### GRAPHICS

Integrated

AMD Radeon<sup>™</sup> Vega Graphics<sup>6</sup>

#### Supports

Support HD decode, DX12, and HDMI2.0

6. HD content required to view HD images.

#### DISPLAY

#### Non-Touch

33.8 cm (13.3") diagonal FHD IPS eDP anti-glare WLED-backlit slim, 250 nits, 45% NTSC (1920 x 1080)<sup>6,8,9</sup> 33.8 cm (13.3") diagonal FHD IPS eDP anti-glare WLED-backlit slim, 250 nits, 45% NTSC with HD camera (1920 x 1080)<sup>6,8,9</sup> 33.8 cm (13.3") diagonal FHD IPS eDP anti-glare WLED-backlit slim, 250 nits, 45% NTSC with HD + IR camera (1920 x 1080)<sup>6,8,9</sup> 33.8 cm (13.3") diagonal FHD IPS eDP anti-glare WLED-backlit slim, 250 nits, 45% NTSC for WWAN (1920 x 1080)<sup>6,8,9</sup> 33.8 cm (13.3") diagonal FHD IPS eDP anti-glare WLED-backlit slim, 250 nits, 45% NTSC for WWAN (1920 x 1080)<sup>6,8,9</sup> 33.8 cm (13.3") diagonal FHD IPS eDP anti-glare WLED-backlit slim, 250 nits, 45% NTSC with HD camera for WWAN (1920 x 1080)<sup>6,8,9</sup>

33.8 cm (13.3") diagonal FHD IPS eDP anti-glare WLED-backlit slim, 250 nits, 45% NTSC with HD + IR camera for WWAN (1920 x 1080)<sup>6,8,9</sup>

33.8 cm (13.3") diagonal FHD IPS eDP + PSR anti-glare WLED-backlit ultraslim, 400 nits, 72% NTSC with Ambient Light Sensor and HD + IR camera (1920 x 1080)<sup>6,8,9</sup>

33.8 cm (13.3") diagonal FHD IPS eDP + PSR anti-glare WLED-backlit ultraslim, 400 nits, 72% NTSC with Ambient Light Sensor and HD + IR camera for WWAN (1920 x 1080)<sup>6,8,9</sup>

33.8 cm (13.3") diagonal FHD IPS eDP + PSR anti-glare WLED-backlit ultraslim with HP Sure View Integrated Privacy Screen, 1000 nits, 72% NTSC with Ambient Light Sensor and HD + IR camera for WWAN (1920 x 1080)<sup>6,7,8,9</sup>

#### Touch

33.8 cm (13.3") diagonal FHD IPS eDP anti-glare On-Cell WLED-backlit slim touch screen, 250 nits, 45% NTSC with HD+IR camera (1920 x 1080)<sup>6,8,9</sup>

33.8 cm (13.3") diagonal FHD IPS eDP anti-glare On-Cell WLED-backlit slim touch screen, 250 nits, 45% NTSC, with HD+IR camera for WWAN (1920 x 1080)<sup>6,8,9</sup>

#### HDMI 2.0

Support resolution up to 4k @ 60Hz

6. HD content required to view HD images.

7. HP Sure View Gen3 integrated privacy panel is an option feature that must be configurated at purchase and is designed to function in landscape orientation. Available in Q3'19.

8. Resolutions are dependent upon monitor capability, and resolution and color depth settings.

9. Sold separately or as an optional feature.



## Features

Docking station model	Total number of supported displays (incl. the notebook display)	Max.resolutions supported	Dock Connectors	Technical limitations
HP UltraSlim Docking Station	4	Dual 2.5K @ 60Hz	2xDP, 1xVGA	Dual 2.5k only with both displays into DP
HP Thunderbolt Dock G2	4	Dual 2560 x 1600 @ 60Hz Single 3840 x 2160 @ 60Hz	2xDP, 1xVGA, 1xTB, 1xUSB-C alt-mode	
HP Elite USB-C Dock G4	4	Dual 2K @ 60Hz Single 4K @ 60Hz (3840 x 1440)	1xHDMI, 2xDP	
HP USB-C Universal Dock	3	Dual 4K @ 60Hz Single 5K @ 60Hz	2xDP	
HP USB-C Travel Dock	2	Single 2K @ 60Hz	1xHDMI, 1xVGA	Single external display Only HDMI or VGA at the time
HP USB-C Mini Dock	2	Single 4K @ 30Hz	1xHDMI, 1xVGA	Single external display Only HDMI or VGA at the time

#### **STORAGE AND DRIVES**

#### Primary M.2 Storage

128 GB SATA-3 SS TLC<sup>10</sup> 256 GB PCIe<sup>®</sup> NVMe<sup>™</sup> Value SS TLC<sup>10</sup> 256 GB PCIe<sup>®</sup> Gen3x4 NVMe<sup>™</sup> SS TLC<sup>10</sup> 256 GB SATA-3 TLC Opal 2<sup>10</sup> 512 GB PCIe<sup>®</sup> Gen3x4 NVMe<sup>™</sup> SS TLC<sup>10</sup> 512 GB PCIe<sup>®</sup> Gen3x4 NVMe<sup>™</sup> SS TLC Opal 2<sup>10</sup> 512 GB PCIe<sup>®</sup> Value<sup>10</sup> 1 TB PCIe<sup>®</sup> Gen3 x4 NVMe<sup>™</sup> SS TLC<sup>10</sup>

10. For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

#### MEMORY

#### Maximum Memory 32 GB DDR4-2400 SDRAM

#### Memory

32 GB DDR4-2400 SDRAM (2 x 16 GB)<sup>11</sup> 16 GB DDR4-2400 SDRAM (1 x 16 GB)<sup>11</sup> 16 GB DDR4-2400 SDRAM (2 x 8 GB)<sup>11</sup> 8 GB DDR4-2400 SDRAM (1 x 8 GB)<sup>11</sup> 8 GB DDR4-2400 SDRAM (2 x 4 GB)<sup>11</sup> 4 GB DDR4-2400 SDRAM (1 x 4 GB)<sup>11</sup>

Memory Slots 2 SODIMM



### Features

Both slots are customer accessible / upgradeable DDR4 SODIMMS, system runs at 2400 Supports Dual Channel Memory

11. Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

#### **NETWORKING/COMMUNICATIONS**

#### WLAN

Intel<sup>®</sup> Dual Band Wireless-AC 9260 802.11a/b/g/n/ac (2x2) Wi-Fi<sup>®</sup> and Bluetooth<sup>®</sup> 5 Combo, non-vPro<sup>™12</sup> Intel<sup>®</sup> AX200 Wi-Fi 6<sup>16</sup> (2x2) and Bluetooth<sup>®</sup> 5 Combo, non-vPro<sup>™</sup> (supporting gigabit file transfer speeds) Realtek RTL8822BE 802.11ac (2x2) and Bluetooth<sup>®</sup> 4.2 Combo<sup>12</sup>

#### WWAN

Intel<sup>®</sup> XMM<sup>™</sup> 7360 LTE-Advanced Cat 9<sup>13</sup>

NFC

NXP NPC300 Near Field Communication Module

#### Miracast

Native Miracast Support<sup>14</sup>

#### Ethernet

Realtek PCIe GbE Family Controller 10/100/1000<sup>15</sup>

12. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited.

13. WWAN module requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.

14. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming. 15. The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

16. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices. Only available in countries where 802.11ax is supported. Feature available in Q3'19.

#### AUDIO/MULTIMEDIA

#### Audio

Audio by Bang & Olufsen Integrated 3 Multi Array Microphone 2 Integrated Stereo Speakers

**Camera** 720p HD camera<sup>6,9</sup> 720p HD+IR camera<sup>6,9,17</sup>

Sensors



## Features

Ambient light sensor (Select models only) Hall Sensor

6. HD content required to view HD images.

- 9. Sold separately or as an optional feature.
- 17. Internet access required.

### **KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS**

#### Keyboard

HP Premium Collaboration Keyboard, spill resistant with drain Backlit keyboard available as an option

#### **Pointing Device**

Clickpad with multi-touch gestures enabled, taps enabled as default Microsoft Precision Touchpad Default Gestures Support

#### **Function Keys**

F1 - Display Switching F2 - Blank or Privacy F3 - Brightness Down F4 - Brightness Up F5 - Audio Mute F6 - Volume Down F7 - Volume Up F8 - Mic Mute F9 - Blank or Backlit Toggle F10 - numlk F11 - Wireless F12 - Calendar Share/Present Call Answer Call End

#### **Hidden Function Keys**

Fn+R - Break Fn+S - Sys Rq Fn+C - Scroll Lock Fn+E - Insert Fn +W – Pause



### Features

### SOFTWARE AND SECURITY

### Preinstalled Software

BIOS HP BIOSphere Gen5<sup>18</sup> HP Drive Lock & Automatic Drive Lock<sup>19</sup> BIOS Update via Network Master Boot Record Security Power On Authentication Secure Erase<sup>20</sup> Absolute Persistence Module<sup>21</sup> Pre-boot Authentication

#### Software

HP Native Miracast Support<sup>22</sup> HP Connection Optimizer HP Image Assistant HP Hotkey Support HP JumpStart HP Support Assistant<sup>23</sup> HP Noise Cancellation Software Buy Office (Sold separately)

#### **Manageability Features**

HP Driver Packs<sup>24</sup> HP System Software Manager (SSM) HP BIOS Config Utility (BCU) HP Client Catalog HP Manageability Integration Kit Gen3<sup>25</sup> HP Cloud Recovery<sup>26</sup>

#### **Client Security Software**

HP Client Security Manager Gen5<sup>27</sup> HP Fingerprint Sensor<sup>28</sup> HP Power On Authentication Windows Defender<sup>29</sup>

#### **Security Management**

Pre-boot Authentication TPM 2.0 Embedded Security Chip shipped with Windows 10 (Common Criteria EAL4+ Certified)<sup>30</sup> SATA 0,1 port disablement (via BIOS) USB enable/disable (via BIOS) Power-on password (via BIOS) Setup password (via BIOS)



### Features

Support for chassis padlocks and cable lock devices HP Sure Click<sup>31</sup> HP Sure Start For AMD<sup>32</sup> Sure Run Gen2<sup>33</sup> Sure Recover Gen2<sup>34</sup> Sure Sense<sup>35</sup>

#### Security

ТРМ

Model: Infineon SLB9670 Version: 7.85 Revision: TPM 2.0 FIPS 140-2 Compliant: Yes (select models only)

#### **Smartcard Reader**

Model number: Alcor AU9560 FIPS 201 Compliant: Yes

#### **IPv6 Certification:**

Yes/No

MD5 Hash: Please follow the instructions below to access MD5 Hash.

Log-on to http://hp.com/support, enter your product name, select software and drivers, select OS, select driver. After selecting the driver, click on "Associated files" and then click on "Download". When opening the file, under "Purpose" you should see the appropriate "SOFTPAQ MD5:" Field

Graphics (Intel Video Driver): TBD

WWAN: TBD

WLAN: TBD

#### Is the BIOS on this notebook ISO/IEC 19678:2015 (formerly NIST 800-147) compliant?:

Yes

UEFI version: 2.6

18. HP BIOSphere Gen5 is available on select HP Pro and Elite PCs. See product specifications for details. Features may vary depending on the platform and configurations.

19. HP Drive Lock & Automatic Drive Lock is not supported on NVMe drives

20. HP Secure Erase for the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel<sup>®</sup> Optane<sup>™</sup>.

21. Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit: http://www.absolute.com/company/legal/agreements/ computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.

22. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming.



### Features

23. HP Support Assistant requires Windows and Internet access.

24. HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.

25. HP Manageability Integration Kit can be downloaded from http://www.hp.com/go/clientmanagement.

26. HP Cloud Recovery is available for HP Elite and Pro desktops and laptops PCs with Intel® or AMD processors and requires an open, wired network connection. Note: You must back up important files, data, photos, videos, etc. before use to avoid loss of data. Detail please refer to: https://support.hp.com/us-en/document/c05115630

27. HP Client Security Manager Gen5 requires Windows and is available on the select HP Pro and Elite PCs. See product specifications for details.

28. HP Fingerprint Sensor sold separately or as an optional feature.

29. Windows Defender Opt in and internet connection required for updates.

30. Firmware TPM is version 2.0. Hardware TPM is v1.2, which is a subset of the TPM 2.0 specification version v0.89 as implemented by Intel Platform Trust Technology (PTT).re TPM is version 2.0. Hardware TPM is v1.2, which is a subset of the TPM 2.0 specification version v0.89 as implemented by Intel Platform Trust Technology (PTT).

31. HP Sure Click is available on most HP PCs and supports Microsoft<sup>®</sup> Internet Explorer and Chromium<sup>™</sup>. Supported attachments include Microsoft Office (Word, Excel, PowerPoint) and PDF files in read only mode, when Microsoft Office or Adobe Acrobat are installed.

32. HP Sure Start for AMD is available on select HP PCs with AMD processors. See product specifications for availability. 33. HP Sure Run Gen2: See product specifications for availability.

34. HP Sure Recover Gen2: See product specifications for availability. Requires an open, wired network connection. Not available on platforms with multiple internal storage drives. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data. HP Sure Recover (Gen1) does not support platforms with Intel<sup>®</sup> Optane<sup>™</sup>. 35. HP Sure Sense requires Windows 10. See product specifications for availability.



### **Features**

#### POWER

#### Power Supply

HP Smart 45 W External AC power adapter<sup>36</sup> HP Smart 45 W External AC power adapter, 2-prong (Japan only)<sup>36</sup> HP Smart 65 W External AC power adapter<sup>36</sup> HP Smart 65 W EM External AC power adapter<sup>36</sup> 45 W USB Type-C<sup>™</sup> adapter<sup>36</sup> 65 W USB Type-C<sup>™</sup> adapter<sup>36</sup>

**Primary Battery** HP Long Life 3-cell, 50 Wh Li-ion<sup>37, 38</sup> Support HP Fast Charge (Up to 50% in 30 minutes with 65W AC Adapter)<sup>37, 38</sup>

#### **Battery Life**

TBD<sup>39</sup>

#### **Power Cord**

2-wire plug - 1.0m<sup>36</sup> 3-wire plug - 1.0m<sup>36</sup> 3-wire plug - 1.8m<sup>36</sup> Duckhead power cord - 1.0m<sup>36</sup> Duckhead power cord - 1.8m<sup>36</sup>

#### 36. Availability may vary by country.

37. Battery is internal and not replaceable by customer. Serviceable by warranty.

38. Recharges the battery up to 50% within 30 minutes when the system is off or in standby mode. Power adapter with a minimum capacity of 65 watts is required. After charging has reached 50% capacity, charging will return to normal. Charging time may vary +/-10% due to System tolerance.

39. Windows 10 MM14 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See <a href="http://www.bapco.com">http://www.bapco.com</a> for additional details.

#### **WEIGHTS & DIMENSIONS**

#### Weight

Starting at 2.94 lb (non-touch); Starting at 3.18 lb (touch)<sup>40</sup> Starting at 1.33 kg (non-touch); Starting at 1.44 kg (touch)<sup>40</sup>

#### Product Dimensions (w x d x h)

**Non-Touch** 12.22 x 9.03 x 0.7 in 31.04 x 22.93 x 1.77 cm

**Touch** 12.22 x 9.03 x 0.7 in 31.04 x 22.93 x 1.79 cm

40. Weight will vary by configuration.



### **Features**

### PORTS/SLOTS

#### Ports

1 USB Type-C<sup>™</sup> (Alt Mode) 2 USB 3.1 Gen 1 (1 charging) 1 HDMI 2.0<sup>41</sup> 1 RJ-45 / Ethernet 1 Docking connector 1 Headphone/microphone combo 1 AC power 1 SIM card slot<sup>42</sup> 1 Smartcard reader<sup>42</sup>

41. HDMI cable sold separately.42. Sold separately or as an optional feature.

#### SERVICE AND SUPPORT

HP Services offers 1-year or 3-year limited warranties and 90 day software limited warranty options depending on country. Batteries have a default one year limited warranty except for Long Life batteries which will have same 1-year or 3-year limited warranty as the platform. Refer to http://www.hp.com/support/batterywarranty/ for additional battery information. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc.<sup>43</sup>

43. HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit <a href="http://www.hp.com/go/cpc">http://www.hp.com/go/cpc</a>. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.



## Technical Specifications

### SYSTEM UNIT

Stand-Alone Power	Nominal Operating Voltage	e 19V
Requirements (AC Power)	Average Operating Power	Win 10
	Integrated Graphics	AMD has no this data (APU is 15 W)
	Max Operating Power	UMA <45 W
Temperature	Operating	32° to 95° F (0° to 35° C)
	Non-operating	-4° to 140° F (-20° to 60° C)
Relative Humidity	Operating	10% to 90%, non-condensing
	Non-operating	5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature
Shock	Operating	40 G, 2 ms, half-sine
	Non-operating	200 G, 2 ms, half-sine
Random Vibration	Operating	0.75 grms
	Non-operating	1.50 grms
Altitude (unpressurized)	Operating	-50 to 10,000 ft (-15.24 to 3,048 m)
	Non-operating	-50 to 40,000 ft (-15.24 to 12,192 m)
Planned Industry Standard	UL	Yes
Certifications	CSA	Yes
	FCC Compliance	Yes
	ENERGY STAR <sup>®</sup>	Yes, Select models <sup>44</sup>
	EPEAT <sup>®</sup> 2019	Yes, Silver in U.S. <sup>45</sup>
	Australia /	Yes
	NZ A-Tick Compliance	
	CCC	Yes
	Japan VCCI Compliance	Yes
	КС	Yes
	BSMI	Yes
	CE Marking Compliance	Yes
	GOST	Yes
	Saudi Arabian Compliance (ICCP)	Yes
	UKRSERTCOMPUTER	Yes

44. Configurations of the HP Elitebook 735 G6 that are ENERGY STAR<sup>®</sup> certified are identified as HP Elitebook 735 G6 ENERGY STAR on HP websites and on http://www.energystar.gov.
45. Based on US EPEAT<sup>®</sup> registration according to IEEE 1680.1-2018 EPEAT<sup>®</sup>. Status varies by country. Visit http://www.epeat.net for more information.



### DISPLAYS

Panel LCD 13.3 inch diagonal 0 FHD (1920 x 1080) Anti-Glare A WLED UWVA 45 percent cg 250 W nits eDP 1.2 w/o PSR slim NWBZ D

Outline Dimensions (W x H)	300.56 x 187.77 mm (max) (w/ PCB & w/o bracket)
Active Area	293.76 x 165.24 mm (typ.)
Weight	260 g (max)
Diagonal Size	13.3 inch
Thickness	3.0 mm (max)
Interface	eDP 1.2 (2 lane)
Surface Treatment	Anti-Glare
Touch Enabled	No
Contrast Ratio	600:1 (typ.)
Refresh Rate	60 Hz
Brightness	250nits (typ.)
Pixel Resolution	1920 x 1080 (FHD)
Format	RGB
Backlight	LED
Color Gamut Coverage	45%
Color Depth	6 bits
Viewing Angle	UWVA 85/85/85/85

Panel LCD 13.3 inch diagonal FHD (1920 x 1080) Anti-Glare WLED UWVA 45 percent cg 250 nits eDP slim Touch on Panel Narrow Bezel

Outline Dimensions (W x H)	300.56 x 187.77
Active Area	293.76 x 165.24 mm (typ.)
Weight	268 g (max)
Diagonal Size	13.3 inch
Thickness	3.2mm (max)
Interface	eDP 1.2
Surface Treatment	Anti-Glare On-cell
Touch Enabled	Yes
Contrast Ratio	600:1 (typ.)
Refresh Rate	60 Hz
Brightness	250 nits
Pixel Resolution	1920 x 1080 (FHD)
Format	RGB
Backlight	LED
Color Gamut Coverage	45%
Color Depth	6 bits
Viewing Angle	UWVA 85/85/85/85



Panel LCD 13.3 inch diagonal
FHD (1920 x 1080) Anti-Glare
WLED UWVA 72 percent cg 400
nits eDP 1.4+PSR2 Ultraslim
Narrow Bezel

Outline Dimensions (W x H)	299.06 x 185.54 mm (max)
Active Area	293.76 x 165.24 mm (typ.)
Weight	170 g (max)
Diagonal Size	13 inch
Thickness	2.0 mm (max)
Interface	eDP 1.4 + PSR2 (2 lane)
Surface Treatment	Anti-Glare
Touch Enabled	No
Contrast Ratio	1200:1 (typ.)
Refresh Rate	60 Hz
Brightness	400 nits
Pixel Resolution	1920 x 1080 (FHD)
Format	RGB
Backlight	LED
Color Gamut Coverage	72%
Color Depth	8 bits
Viewing Angle	UWVA 85/85/85/85

Panel LCD 13.3 inch diagonal
FHD (1920 x 1080) Anti-Glare
WLED UWVA 72percent cg
1000nits eDP 1.4+PSR2 flat
Privacy Narrow Bezel*

Outline Dimensions (W x H)	299.06 x 186.54 mm (max)
Active Area	293.76 x 165.24 mm (typ.)
Weight	255 g (max)
Diagonal Size	13.3 inch
Thickness	3.0 mm (max)
Interface	eDP 1.4 + PSR2 (4 lane)
Surface Treatment	Anti-Glare (AG)
Touch Enabled	No
Contrast Ratio	2000:1 (typ.)
Refresh Rate	60 Hz
Brightness	1000 nits
Pixel Resolution	1920 x 1080 (FHD)
Format	RGB
Backlight	LED
Color Gamut Coverage	72%
Color Depth	8 bits
Viewing Angle	UWVA 85/85/85/85

\*Available in Q3'19

All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.



### STORAGE

SSD 128 GB 2280 M2 SATA-3 TLC	Form Factor	M.2 2280
	Capacity	128 GB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	ATA-8, SATA 3.0
	Maximum Sequential Read	Around 540 ~ 560 MB/s
	Maximum Sequential Write	Around 380 ~ 530 MB/s
	Logical Blocks	250069680
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security; DIPM; TRIM; DEVSLP
SSD 1 TB 2280 PCIe-3x4 NVMe Three Layer Cell single-sided	Form Factor Capacity NAND Type	M.2 2280 1 TB TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen3X4
	Maximum Sequential Read	Around 3200 ~ 3480 MB/s
	Maximum Sequential Write	Around 2400 ~ 3037 MB/s
	Logical Blocks	2000409264
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security; TRIM; L1.2

SSD 256 GB 2280 M2 PCIe-3x4 SS	Form Factor	M.2 2280
NVMe TLC	Capacity	256 GB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen3X4
	Maximum Sequential Read	Around 2900 ~ 3167 MB/s
	Maximum Sequential Write	Around 1300 ~ 1663 MB/s
	Logical Blocks	500118192
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]



## Technical Specifications

	Features	ATA Security; TRIM; L1.2
SSD 256 GB 2280 M2 SATA-3 Self	Form Factor	M.2 2280
ncrypted OPAL2 Three Layer	Capacity	256 GB
Cell	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	ATA-8, SATA 3.0
	Maximum Sequential Read	Around 530 ~ 560 MB/s
	Maximum Sequential Write	Around 500 ~ 530 MB/s
	Logical Blocks	500118192
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security; TCG OPAL 2.0; DIPM; TRIM; DEVSLP
SSD 256 GB 2280 PCIe NVMe	Form Factor	M.2 2280
Value	Capacity	256 GB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen3X4
	Maximum Sequential Read	Around 1500 ~ 1700 MB/s
	Maximum Sequential Write	Around 780 ~ 1300 MB/s
	Logical Blocks	500118192
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security; TRIM; L1.2
SSD 512 GB 2280 M2 PCIe-3x4 SS NVMe TLC		M.2 2280
nvric ILL	Capacity	512 GB
	NAND Type	
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen3X4
	Maximum Sequential Read	
	Maximum Sequential Write	Around 1390 ~ 2956 MB/s



# Technical Specifications

	Logical Blocks	
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security; TRIM; L1.2
SSD 512 GB 2280 PCIe NVMe	Form Factor	M.2 2280
Value	Capacity	512 GB
	NAND Type	TLC/QLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen3X4
	Maximum Sequential Read	Around 1500 ~ 1700 MB/s
	Maximum Sequential Write	Around 860 ~ 1500 MB/s
	Logical Blocks	1000215215
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security; TRIM; L1.2
SSD 512 GB 2280 PCIe-3x4 NVMe	Form Factor	M.2 2280
Self Encrypted OPAL2 Three Layer Cell	Capacity	512 GB
Layer Cell	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen3X4
	Maximum Sequential Read	Around 2900 ~ 3400 MB/s
	Maximum Sequential Write	Around 1000 ~ 2500 MB/s
	Logical Blocks	1000215216
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security; TCG Opal 2.0; FIPS; DIPM; TRIM; DEVSLP



### **NETWORKING/COMMUNICATIONS**

Intel® 9260	Wireless LAN Standards	IEEE 802.11a
802.11a/b/g/n/ac (2 x 2)		IEEE 802.11b
Wi-Fi <sup>®</sup> and Bluetooth <sup>®</sup> 5.0 Combo <sup>1</sup> Non-vPro		IEEE 802.11g
		IEEE 802.11n
		IEEE 802.11ac
		IEEE 802.11d
		IEEE 802.11e IEEE 802.11h
		IEEE 802.1111 IEEE 802.111
		IEEE 802.11k
		IEEE 802.11r
		IEEE 802.11v
	Interoperability	Wi-Fi <sup>®</sup> certified
	Frequency Band	802.11b/g/n
		• 2.402 – 2.482 GHz
		802.11a/n/ac • 4.9 – 4.95 GHz (Japan)
		• 5.15 – 5.25 GHz
		• 5.25 – 5.35 GHz
		• 5.47 – 5.725 GHz
		• 5.825 – 5.850 GHz
	Data Rates	•802.11b: 1, 2, 5.5, 11 Mbps
		•802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
		•802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
		•802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) •802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, 80MHz &
		160MHz)
	Modulation	Direct Sequence Spread Spectrum
		BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
	Security <sup>3</sup>	•IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only
		•AES-CCMP: 128 bit in hardware
		•802.1x authentication
		<ul> <li>WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.</li> <li>WPA2 certification</li> </ul>
		•IEEE 802.11i
		•WAPI
	Network Architecture	Ad-hoc (Peer to Peer)
	Models	Infrastructure (Access Point Required)
	Roaming	IEEE 802.11 compliant roaming between access points
	Output Power <sup>2</sup>	• 802.11b: +18.5dBm minimum
		• 802.11g: +17.5dBm minimum
		• 802.11a: +18.5dBm minimum
		• 802.11n HT20(2.4GHz): +15.5dBm minimum
		• 802.11n HT40(2.4GHz): +14.5dBm minimum • 802.11n HT20(5GHz): +15.5dBm minimum



# Technical Specifications

Power Consumption	<ul> <li>802.11n HT40(5GHz): +14.5dBm minimum</li> <li>802.11ac VHT80(5GHz): +11.5dBm minimum</li> <li>802.11ac VHT160(5GHz): +11.5dBm minimum</li> <li>Transmit mode 2.0 W</li> <li>Receive mode 1.6 W</li> <li>Idle mode (PSP) 180 mW (WLAN Associated)</li> <li>Idle mode 50 mW (WLAN unassociated)</li> <li>Connected Standby/Modern 10mW</li> <li>Radio disabled 8 mW</li> </ul>	
Power Management	ACPI compliant power m 802.11 compliant power	-
Receiver Sensitivity <sup>4</sup>	802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum	
Antenna type	enclosure Two embedded dual ban	with spatial diversity, mounted in the display d 2.4/5 GHz antennas are provided to the card to nmunications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard	
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm	
Weight	1. Type 2230: 2.8g 2. Type 126: 1.3g	
Operating Voltage	3.3v +/- 9%	
Temperature	Operating Non-operating	14° to 158° F (–10° to 70° C) –40° to 176° F (–40° to 80° C)
Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)
Altitude	Operating Non-operating	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)
LED Activity	<b>LED Amber</b> – Radio OFF <b>LED OFF</b> – Radio ON	

#### HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0 Wireless Technology

Bluetooth Specification	4.0/4.1/4.2/5.0 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available	Legacy: 0~79 (1 MHz/CH)
Channels	BLE: 0~39 (2 MHz/CH)



<b>Technical Specif</b>	ications	
	Signaling Data Rate	Legacy: 3 Mbps signaling data rate <sup>1</sup> 2.17 Mbps BLE: 1 Mbps signaling data rate <sup>1</sup> 0.2 Mbps 1. Actual throughput may vary.
		Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels
		Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
	Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.
	Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
	<b>Electrical Interface</b>	USB 2.0 compliant
	Bluetooth Software Supported	Microsoft Windows Bluetooth Software
	Power Management	Microsoft Windows ACPI, and USB Bus Support
	Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
	Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
	Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

1. Wireless access point and Internet service is required. Availability of public wireless access point is limited.

2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

3. Check latest software/driver release for updates on supported security features.

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).



802.11a/b/g/n/ac (2 x 2) Wi-Fi® and Bluetooth® 4.2 Combo <sup>1</sup>	Wireless LAN Standards Interoperability	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac Wi-Fi® certified
	Frequency Band	802.11b/g/n • 2.402 – 2.482 GHz 802.11a/n • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz
	Data Rates	<ul> <li>802.11b: 1, 2, 5.5, 11 Mbps</li> <li>802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps</li> <li>802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps</li> <li>802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)</li> <li>802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)</li> </ul>
	Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
	Security <sup>3</sup>	<ul> <li>IEEE and Wi-Fi compliant 64 / 128 bit WEP encryption for a/b/g mode only</li> <li>AES-CCMP: 128 bit in hardware</li> <li>802.1x authentication</li> <li>WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.</li> <li>WPA2 certification</li> <li>IEEE 802.11i</li> <li>WAPI</li> </ul>
	Network Architecture	Ad-hoc (Peer to Peer)
	Models Roaming	Infrastructure (Access Point Required) IEEE 802.11 compliant roaming between access points
	Output Power <sup>2</sup>	<ul> <li>802.11b: +14dBm minimum</li> <li>802.11g: +12dBm minimum</li> <li>802.11a: +12dBm minimum</li> <li>802.11n HT20(2.4GHz): +12dBm minimum</li> <li>802.11n HT40(2.4GHz): +12dBm minimum</li> <li>802.11n HT20(5GHz): +10dBm minimum</li> <li>802.11n HT40(5GHz): +10dBm minimum</li> <li>802.11ac VHT80(5GHz): +10dBm minimum</li> </ul>
	Power Consumption	<ul> <li>Transmit mode 2.0 W</li> <li>Receive mode 1.6 W</li> <li>Idle mode (PSP) 180 mW (WLAN Associated)</li> <li>Idle mode 50 mW (WLAN unassociated)</li> </ul>



## Technical Specifications

	<ul> <li>Connected Standby 10</li> <li>Radio disabled 8 mW</li> </ul>	mW
Power Management	ACPI and PCI Express of power saving mode	compliant power management 802.11 compliant
Receiver Sensitivity <sup>3</sup>	802.11b, 1Mbps: -93.5d 802.11b, 11Mbps: -84dE 802.11a/g, 6Mbps: -86d 802.11a/g, 54Mbps: -72 802.11n, MCS07: -67dBr 802.11n, MCS15: -64dBr 802.11ac, MCS0: -84dBr 802.11ac, MCS9: -59dBr	8m maximum Bm maximum dBm maximum m maximum n maximum n maximum
Antenna type	enclosure Two embedded dual bar	with spatial diversity, mounted in the display Id 2.4/5 GHz antennas are provided to the card to Inmunications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCar	d
Dimensions	Type 2230: 2.3 x 22.0 x 3	30.0 mm
Weight	Type 2230: 2.8g	
Operating Voltage	3.3v +/- 9%	
Temperature	Operating Non-operating	14° to 158° F (–10° to 70° C) –40° to 176° F (–40° to 80° C)
Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)
Altitude	Operating Non-operating	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)
LED Activity	<b>LED Amber</b> – Radio OFF <b>LED OFF</b> – Radio ON	

### HP Integrated Module with Bluetooth 4.0/4.1/4.2 Wireless Technology

<b>Bluetooth Specification</b>	4.0/4.1/4.2 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Signaling Data Rate	Legacy: 3 Mbps signaling data rate <sup>1</sup> 2.17 Mbps BLE: 1 Mbps signaling data rate <sup>1</sup> 0.2 Mbps 1. Actual throughput may vary.

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels



## **Technical Specifications**

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
<b>Electrical Interface</b>	USB 2.0 compliant
Bluetooth Software Supported	Microsoft Windows Bluetooth Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

1. Wireless access point and Internet service is required. Availability of public wireless access point is limited.

2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

3. Check latest software/driver release for updates on supported security features.

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).



Intel® Wi-Fi® 6 <sup>5</sup> AX200 + BT5 (802.11ax 2 x 2, non- vPro, supporting gigabit file transfer speeds) non-vPro		IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11h IEEE 802.11i IEEE 802.11r IEEE 802.11r IEEE 802.11v
	Interoperability	Wi-Fi <sup>®</sup> certified
	Frequency Band	802.11b/g/n/ax • 2.402 – 2.482 GHz 802.11a/n/ac/ax • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz
	Data Rates	<ul> <li>•802.11b: 1, 2, 5.5, 11 Mbps</li> <li>•802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps</li> <li>•802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps</li> <li>•802.11a: MCS 0 ~ MCS 15, (20MHz, and 40MHz)</li> <li>•802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, 80MHz &amp; 160MHz)</li> <li>• 802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, 80MHz &amp; 160MHz)</li> </ul>
	Modulation	Direct Sequence Spread Spectrum OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM
	Security <sup>3</sup>	<ul> <li>IEEE and Wi-Fi compliant 64 / 128 bit WEP encryption for a/b/g mode only</li> <li>AES-CCMP: 128 bit in hardware</li> <li>802.1x authentication</li> <li>WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.</li> <li>WPA2 certification</li> <li>IEEE 802.11i</li> <li>WAPI</li> </ul>
	Network Architecture	Ad-hoc (Peer to Peer)
	Models	Infrastructure (Access Point Required)
	Roaming Output Power <sup>2</sup>	IEEE 802.11 compliant roaming between access points • 802.11b: +18.5dBm minimum • 802.11g: +17.5dBm minimum • 802.11a: +18.5dBm minimum • 802.11n HT20(2.4GHz): +15.5dBm minimum



## Technical Specifications

Power Consumption	<ul> <li>802.11n HT40(2.4GHz</li> <li>802.11n HT20(5GHz):</li> <li>802.11n HT40(5GHz):</li> <li>802.11ac VHT80(5GHz</li> <li>802.11ac VHT160(5GHz</li> <li>802.11ax HT40(2.4GHz</li> <li>802.11ax VHT160(5GHz</li> <li>8</li></ul>	+15.5dBm minimum +14.5dBm minimum z): +11.5dBm minimum Hz): +11.5dBm minimum z): +10dBm minimum Hz): +10dBm minimum MW (WLAN Associated) AN unassociated)
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode	
Receiver Sensitivity <sup>3</sup>	•802.11b, 1Mbps: -93.5 •802.11b, 11Mbps: -84 • 802.11a/g, 6Mbps: -86 • 802.11a/g, 54Mbps: - • 802.11n, MCS07: -67d • 802.11n, MCS15: -64d • 802.11ac, MCS0: -84d • 802.11ac, MCS9: -59d •802.11ax, MCS11(HT46	dBm maximum 6dBm maximum 72dBm maximum IBm maximum IBm maximum Bm maximum Bm maximum
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications	
Form Factor	PCI-Express M.2 MiniCard	
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm	
Weight	1. Type 2230: 2.8g 2. Type 126: 1.3g	
Operating Voltage	3.3v +/- 9%	
Temperature	Operating Non-operating	14° to 158° F (–10° to 70° C) –40° to 176° F (–40° to 80° C)
Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)
Altitude	Operating Non-operating	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology



<b>Bluetooth Specification</b>	4.0/4.1/4.2/5.0/5.1 Compliant	
Frequency Band	2402 to 2480 MHz	
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)	
Signaling Data Rate	Legacy: 3 Mbps signaling data rate <sup>1</sup> 2.17 Mbps BLE: 1 Mbps signaling data rate <sup>1</sup> 0.2 Mbps 1. Actual throughput may vary.	
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels	
	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)	
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 9.5 dBm for BR and EDR.	
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW	
	Selective Suspend 17 mW	
Bluetooth Software Supported	Microsoft Windows Bluetooth Software	
Power Management	Microsoft Windows ACPI, and USB Bus Support	
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249	
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark	
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)	

Wireless access point and Internet service is required. Availability of public wireless access point is limited.
 The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.



3. Check latest software/driver release for updates on supported security features.

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

5. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices. Only available in countries where 802.11ax is supported. Feature available in Q3'19.

Intel® XMM™ 7360 LTE- Advanced CAT9¹	Technology/Operating bands	FDD LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3), 1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 1400 (Band 11), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 17 lower), 850 (Band 18 lower), 850 (Band 19 upper), 800 (Band 20), 1400 (Band 21), 850 (Band 26), 700 (Band 28), 700 (Band 29 RX only), 2300 (Band 30), 1700/2100 (Band 66). TDD LTE: 2600 (Band 38), 1900 (Band 39), 2400 (Band 40), 2500 (Band 41). HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4), 850 (Band 5), 900 (Band 8) MHz
	Wireless protocol standards	3GPP Release 11 LTE Specification CAT.9, DL 60MHz BW throughput up to 450Mbps; UL 20MHz throughput up to 50Mbps WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification
	GPS	Standalone, A-GPS (MS-A, MS-B)
	GPS bands	1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou 1561.098 MHz
	Maximum data rates	LTE: 450 Mbps (Download), 50 Mbps (Upload) DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76 Mbps (Upload)
	Maximum output power	LTE: 23 dBm HSPA+: 23.5 dBm
	Maximum power consumption	LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average)
	Form Factor	M.2, 3042-S3 Key B
	Weight	5.8 g
	Dimensions (Length x Width x Thickness)	42 x 30 x 2.3 mm

1. Mobile Broadband is an optional feature. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. WWAN is an optional feature, requires factory configuration and separately purchased service contract. Check with service provider for coverage and availability in your area. 4G LTE not available on all products, in all regions.



# Technical Specifications

Near Field	Dimensions (L x W x H)	Module 25 mm by 10 mm by 2.0 mm
Communications	Chipset	NPC300
Controller (optional)	System interface	I2C
	NFC RF standards	ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 ISO/IEC 18092 ECMA-340 NFCIP-1 Target and Initiator ECMA-320 NFCIP-2
	NFC Forum Support	Tag Type 1, Type 2, Type3 and Type 4, NFCIP-1 and NFCIP-2
	Reader (PCD-VCD) Mode(1)	ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 MIFARE 1K MIFARE 4K MIFARE DESFire FeliCa Jewel and Topaz cards
	Card Emulation (PICC-VICC) Mode(1)	ISO/IEC 14443 A ISO/IEC 14443 B and B' MIFARE FeliCa
	Frequency	13.56 MHz
	NFC Modes Supported	Reader/Writer, Peer-to-Peer
	Raw RF Data Rates	106, 212, 424, 848 kbps
	Operating temperature	0°C to 70°C
	Storage temperature	-20°C to 125°C
	Humidity	10-90% operating 5-95% non-operating
	Supply Operating voltage	4.35 to 5.25 Volts
	I/O Voltage	1.8V or 3.3V
Power Consumption	Mode	Power Consumption, Typical
(Booster enable, VBAT=	Polling	710.93 mW
3.3V, VCC_BOOST = 5V)	Detected Test Tag Type 1	152.09 mW
	Detected Test Tag Type 2	
	Detected Test Tag Type 3	383.76 mW
	Detected Test Tag Type 4	312.26 mW
	Antenna	Antenna connector, 0.5mm pitch, 7 connector FPC. Antenna matching is external to module.



# Technical Specifications

Realtek RTK8111EPH	Connector	RJ-45				
10/100/1000 Integrated NIC	System Interface	PCIe + SMBus				
	Data rates supported	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21- 30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s				
	IEEE Compliance	IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) IEEE 802.3az EEE (Energy Efficient Ethernet)				
	Performance	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling Jumbo Frame 9K				
	Power consumption	Cable Disconnection: 25mW 100Mbps Full Run: 450mW 1000bp Full Run: 1000mW WoL Enable(S3/S4/S5): 50mW WoL Disable(S3/S4/S5): 25mW				
	Power Management	ACPI compliant – multiple power modes Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption				
	Management Interface	Auto MDI/MDIX Crossover cable detection				
	IT Manageability	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status				
	Security & Manageability	RTK DASH support with appropriate RTK chipset components				

### POWER

AC Adapter 45 Watt nPFC Wall Mount USB type C Straight 1.8 m C6NS	Dimensions Weight Input	62.0 x 62.0 x 28.5 mm unit: 220 g +/- 10 g Input Efficiency	Average Efficiency of 25%, 50%, 75%, 100% load condition with 115Vac/230Vac Spec: 5V: 81.5% 9V: 86.7% 10V: 87.5% 12V: 87.8% 15V: 87.8% 20V: 87.8%
		Input frequency range	47 ~ 63 Hz
		Input AC current	Max. 1.4 A at 90 Vac
	Output	Output power	Average Efficiency of 25%, 50%, 75%, 100% load condition with 115Vac/230Vac Spec
		DC output	5V: 81.5%
		Hold-up time	9V: 86.7%
	Connector	Output current limit Non-Standard C6	10V: 87.5%
	Environmental Design	Operating temperature	32°F to 95°F (0° to 35°C)
		Non-operating (storage) temperature	-4°F to 185°F (-20°to 85°C)
		Altitude	0 to 16,400 ft (0 to 5000m)
		Humidity	20% to 95%
		Storage Humidity	10% to 95%
	EMI and Safety Certifications	Worldwide safety standard SELV; Agency approvals – FCC Class B, CISPR22 Class	with LVD and EMC directives ds - IEC60950, EN60950, UL60950, Class1, C-UL-US, NORDICS, DENAN, EN55022 Class B, B, CCC, NOM-1 NYCE. s at 25°C ambient condition.

AC Adapter 45 Watt Smart nPFC Standard Barrel 4.5 mm Right Angle 1.8 m	Dimensions Weight Input	95.0 x 40.0 x 26.5 mm unit: 200 g +/- 10 g Input Efficiency Input frequency range Input AC current	87.74 % at 115 Vac and 88.4 % at 230Vac 47 ~ 63Hz Max. 1.4 A at 90 Vac
	Output Connector	Output power DC output Hold-up time Output current limit C6	45 W 19.5 V 5ms at 115 Vac input <8.0A
	Environmental Design	Operating temperature Non-operating (storage) temperature Altitude Humidity	32°F to 95°F (0°to 35°C) -4°F to 185°F (-20° to 85°C) 0 to 16,400 ft (0 to 5000m) 20% to 95%



Technical Specific	ations		
		Storage Humidity	10% to 95%
	Safety Certifications	Worldwide safety standar SELV; Agency approvals – FCC Class B, CISPR22 Class	with LVD and EMC directives ds - IEC60950, EN60950, UL60950, Class1, C-UL-US, NORDICS, DENAN, EN55022 Class B, 5 B, CCC, NOM-1 NYCE. s at 25°C ambient condition.
AC Adapter 45 Watt	Dimensions	95.0 x 40.0 x 26.5 mm	
Smart nPFC Standard	Weight	unit: 200 g +/- 10 g	
Barrel 4.5 mm Right Angle 1.8 m 2prong	Input	Input Efficiency	87.74 % at 115 Vac and 88.4 % at 230Vac
Angle 1.0 m 2prong	-	Input frequency range	47 ~ 63 Hz
		Input AC current	Max. 1.4 A at 90 Vac
	Output	Output power	45W
		DC output	19.5V
		Hold-up time Output current limit	5ms at 115 Vac input <8.0A
	Connector	C8	
	Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)
		Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)
		Altitude	0 to 16,400 ft (0 to 5000m)
		Humidity	20% to 95%
		Storage Humidity	10% to 95%
	Safety Certifications	Worldwide safety standar SELV; Agency approvals – FCC Class B, CISPR22 Class	with LVD and EMC directives ds - IEC60950, EN60950, UL60950, Class1, C-UL-US, NORDICS, DENAN, EN55022 Class B, 5 B, CCC, NOM-1 NYCE. s at 25°C ambient condition.
	Dimensione	747420.5	
AC Adapter 65 Watt nPFC USB type C Straight 1.8 m	Dimensions	74 x 74 x 28.5 mm	
C6NS	Weight	unit: 245 g +/- 10 g	
	Input	Input Efficiency	81.5% min at 115 Vac/ 230Vac @ 5V/3A 86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 10V/5A 88% min at 115 Vac/ 230Vac @ 12V/5A 89% min at 115 Vac/ 230Vac @ 15V/4.33A 89% min at 115 Vac/ 230Vac @ 20V/3.25A
		Input frequency range	47 ~ 63 Hz
		Input AC current	1.7 A at 90 VAC and maximum load
	Output	Output power	65W
		DC output	5V/9V/10V/12V/15V/20V
		Hold-up time	5ms at 115 Vac input
	Connect	Output current limit	<8.0A
	Connector	Non-Standard C6	
	Environmental Design	Operating temperature	32°F to 95°F (0°to 35°C)



# Technical Specifications

	Non-operating (storage) temperature	-4°F to 185°F (-20° to 85°C)
	Altitude	0 to 16,400 ft (0 to 5000m)
	Humidity	5% to 95%
	Storage Humidity	5% to 95%
Safety Certifications	Worldwide safety standard SELV; Agency approvals - ( FCC Class B, CISPR22 Class	vith LVD and EMC directives ds - IEC60950, EN60950, UL60950, Class1, C-UL-US, NORDICS, DENAN, EN55022 Class B, B, CCC, NOM-1 NYCE. s at 25°C ambient condition.

AC Adapter 65 Watt Smart nPFC EM Barrel	Dimensions Weight	102 x 55 x 30 mm unit: 250 g +/- 10 g	
4.5 mm New EM	Input	Input Efficiency	88.0 % at 115 Vac and 89.0 % at 230Vac
		Input frequency range	47 ~ 63 Hz
		Input AC current	Max. 1.7 A at 90 Vac
	Output	Output power	65W
	-	DC output	19.5V
		Hold-up time	5ms at 115 Vac input
		Output current limit	<11.0A
	Connector	C6	
	Environmental Design	Operating temperature	32° F to 95° F (0° to 35° C)
		Non-operating (storage) temperature	-4° F to 185° F (-20° to 85° C)
		Altitude	0 to 16,400 ft (0 to 5000m)
		Humidity	20% to 95%
		Storage Humidity	10% to 95%
	Safety Certifications	CE Mark - full compliance with LVD and EMC directives Worldwide safety standards - IEC60950, EN60950, UL60950, Class SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Cla FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. MTBF - over 200,000 hours at 25°C ambient condition.	

AC Adapter 65 Watt Smart nPFC Standard Barrel 4.5 mm Right Angle 1.8 m	Dimensions Weight Input	90.0 x 51 x 28.5 mm unit: 230 g +/- 10 g Input Efficiency 88.0 % at 115 Vac and 89.0 % at 230Vac		
		Input frequency range	47 ~ 63 Hz	
		Input AC current	Max. 1.7 A at 90 Vac	
	Output	Output power	65W	
		DC output	19.5V	
		Hold-up time	5ms at 115 Vac input	
		Output current limit	<11.0A	
	Connector	C6		
	Environmental Design	Operating temperature	32° F to 95° F (0° to 35° C)	



		temperature	-4° F to 185° F (-20° to 85° C)	
		Altitude	0 to 16,400 ft (0 to 5000m)	
		Humidity	20% to 95%	
		Storage Humidity	10% to 95%	
Safety Certifications		CE Mark - full compliance with LVD and EMC directives Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. MTBF - over 200,000 hours at 25°C ambient condition.		
Battery SS 3 Cell 50 WHr Long Life -PL	Dimensions Weight	L 278.7 mm x W 76.3 mm x H 7.1 mm 193 g +/- 10 g		
	Cells/Type	3cell Lithium-Ion Polymer cell / P604883A1		
		Voltage	11.55 V	
	Energy	Amp-hour capacity	4.113 Ah/ 4.330 Ah	
		Watt-hour capacity	50 Wh	
	<b>_</b> .	Operating (Charging)	0° to 50° C	
	Temperature	Operating (Discharging)	-10° to 60° C	
	Warranty	Based on system offering		
	Optional Travel Battery Available	No		

#### **COUNTRY OF ORIGIN**

China



## Options and Accessories (sold separately and availability may vary by country)

•		<i>y</i>
Туре	Description	Part #
Cases	HP Essential Top Load Case (up to 15.6")	H2W17AA
	HP Slim Ultrabook Top Load	F3W15AA
	HP Basic/Essential Backpack	H1D24AA
	HP Exec Midnight 15.6" Backpack	1KM16AA
Docking	HP UltraSlim Docking Station	D9Y32AA
	HP Thunderbolt Dock 120W G2	2UK37AA
	HP TB Dock Audio Module	3AQ21AA
	HP TB Dock 120W G2 cable	3XB94AA
	HP TB Dock G2 combo cable	3XB96AA
	HP USB-C Dock G4	3FF69AA
	HP USB-C Mini Dock	1PM64AA
	HP USB Travel Dock	T0K30AA
	HP USB-C Universal Dock	1MK33AA
	HP USB-C Universal Dock w/4.5mm Adapter	2UF95AA
	HP USB-C Universal Dock w/4.5mm Adapter - non-flash version	3DV65AA
	HP USB-C Dock G5	5TW10AA
	HP USB-C/A Universal Dock G2	5TW13AA
	HP Adjustable Dual Display Stand	AW664AA
	HP Display and Notebook Stand II	E8G00AA
Input/Output	HP Slim Wireless Keyboard and Mouse	T6L04AA
	HP Slim USB Keyboard and Mouse	T6T83AA
	HP Wireless (Link-5) Keyboard	T6U20AA
	HP USB Essential Keyboard and Mouse	H6L29AA
	HP Conferencing Keyboard	K8P74AA
	HP USB Collaboration Keyboard	Z9N38AA
	HP Wireless Collaboration Keyboard	Z9N39AA
	HP Comfort Grip Wireless Mouse	H2L63AA
	HP X4000b Bluetooth Mouse	H3T50AA
	HP 3-Button USB Laser Mouse	H4B81AA
	HP USB Travel Mouse	G1K28AA
	HP Ultra Mobile Wireless Mouse	H6F25AA
	HP Slim Bluetooth Mouse to AMO	F3J92AA
	HP Wireless Premium Mouse	1JR31AA
	HP USB Premium Mouse	1JR32AA
	HP Essential USB Mouse	2TX37AA
	HP Elite Presenter Mouse	2CE30AA
	HP Stereo 3.5mm Headset	T1A66AA
	HP Stereo USB Headset	T1A67AA
	HP UC Wireless Mono Headset	W3K08AA
	HP UC Wireless Duo Headset	W3K09AA



## Options and Accessories (sold separately and availability may vary by country)

-		
	HP USB-C to USB 3.0 Adapter	N2Z63AAA
	HP USB-C to USB-A Hub	Z6A00AA
	HP USB-C to DP	N9K78AA
	HP USB-C to VGA	N9K76AA
	HP HDMI to DVI	F5A28AA
	HP HDMI to VGA	H4F02AA
	HP USB-C to HDMI 2.0 Adapter	1WC36AA
Power	HP 65W Slim AC Adapter	H6Y82AA
	HP 90W Slim AC Adapter	Н6Ү8ЗАА
	HP 90W Slim Combo AC Adapter w/ USB	H6Y84AA
	HP 45W Smart AC Adapter	H6Y88AA
	HP 65W Smart AC Adapter	H6Y89AA
	HP 90W Smart AC Adapter	H6Y90AA
	HP 45W 2-prong 4.5 mm DC jack AC Adapter	L6F60AA
	HP 45W USB-C Power Adapter	1HE07AA
	HP 65W USB-C Power Adapter	1HE08AA
	65W USB-C Slim Power Adapter	3PN48AA
	HP Notebook Power Bank	N9F71AA
	HP USB-C Notebook Power Bank	1TZ86AA
Memory	HP 4GB 2400MHz DDR4 Memory	Z4Y84AA
	HP 8GB 2400MHz DDR4 Memory	Z4Y85AA
	HP 16GB 2400MHz DDR4 Memory	Z4Y86AA
Storage	HP USB External DVDRW Drive	F2B56AA
	HP 256GB M2 PCIe NVME SSD TLC (2280)	1FU87AA
	HP 512GB M2 PCIe NVME SSD TLC 2280)	1FU88AA
Security	HP Docking Station Cable Lock	AU656AA
	HP Essential Combination Lock	T0Y16AA
	HP Combination Lock	TOY15AA
	HP Keyed Cable lock	TOY14AA
	HP Keyed Cable Lock 10mm	T1A62AA
	HP Dual Head Keyed Cable Lock	T1A64AA



## Summary of Changes Change Log

Date of change:	Version History:	Description of change:
	V1 to V2	

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